

PC353T

Opaque*, Mini-flat Package Photocoupler with Base Terminal

■ Features

- With base terminal
- Applicable to infrared ray reflow (230°C, MAX. 30 seconds)
- High isolation voltage (V_{iso} : 3 750V_{rms})
- Recognized by UL, file No. E64380
- Mini-flat package

* Employed double transfer mold technology.

■ Applications

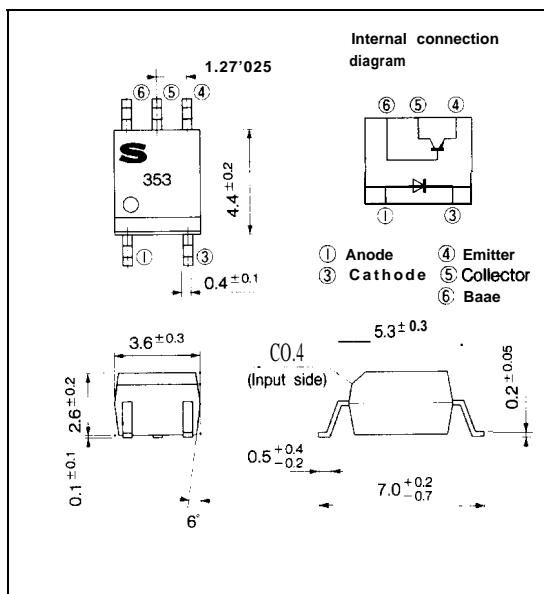
- Hybrid substrates that require high density mounting
- Programmable controllers

■ Package Specifications

Model No.	Taping specifications
PC353T	Taping reel diameter φ178mm (750pcs.)

■ Outline Dimensions

(Unit : mm)



■ Absolute Maximum Ratings

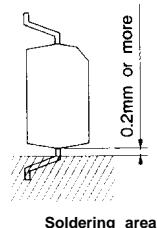
(Ta = 25°C)

Parameter	Symbol	Rating	Unit
Input	I _F	50	mA
	I _{FM}	1	A
	V _R	6	V
	P	70	mW
output	V _{CEO}	80	V
	V _{ECO}	6	V
	V _{CBO}	80	V
	V _{EBO}	6	V
	I _C	50	mA
	P _C	150	mW
	P _{tot}	170	mW
Isolation voltage	V _{iso}	3.75	kV _{rms}
Operating temperature	T _{opr}	-30 to 100	°C
Storage temperature	T _{stg}	-40 to 125	°C
Soldering temperature	T _{sot}	260	°C

*1 Pulse width 100 μs, Duty ratio : 0.001

*2 AC for 1 min., 40 to 60%RH, f=60Hz

*3 For 10 seconds



Soldering area

■ Electro-optical Characteristics

(Ta = 25°C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input	Forward voltage	V _F	I _F = 20mA	—	10	250	μ A
	Reverse current	I _R	V _R = 4V				
	Terminal capacitance	C _t	V = 0, f = 1kHz				
output	Collector dark current	I _{CEO}	V _{CE} = 20V, I _F = 0	80	—	100	nA
	Collector -emitter breakdown voltage	BV _{CEO}	I _C = 0.1mA I _F = 0				
	Emitter-collector breakdown voltage	BV _{ECO}	I _E = 10 μ A I _F = 0		6	—	V
	Collector -base breakdown voltage	BV _{CBO}	I _C = 0.1mA I _F = 0				
Transfer characteristics	Collector current	I _C	I _F = 5mA V _{CE} = 5V	2.5	—	30	mA
	Collector -emitter saturation voltage	V _{CE(sat)}	I _F = 20mA I _C = 1mA				
	Isolation resistance	R _{ISO}	DC500V 40 to 60% RH		1x 10 ¹⁰	10 ¹¹	Ω
	Floating capacitance	C _f	V = 0, f = 1MHz				
	Rise time	t _r	V _{CE} = 2V, I _C = 2mA		—	0.6	1.0
	Fall time	t _f	R _L = 100 Ω				

Fig. 1 Forward Current vs.
Ambient Temperature

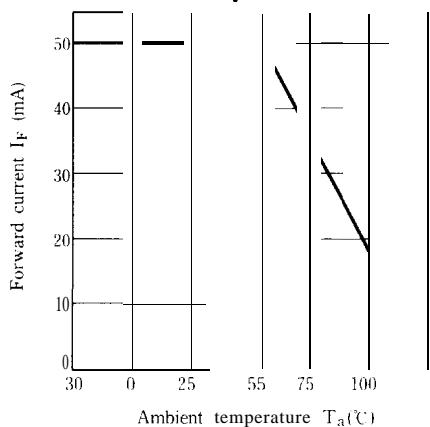


Fig. 2 Diode Power Dissipation vs.
Ambient Temperature

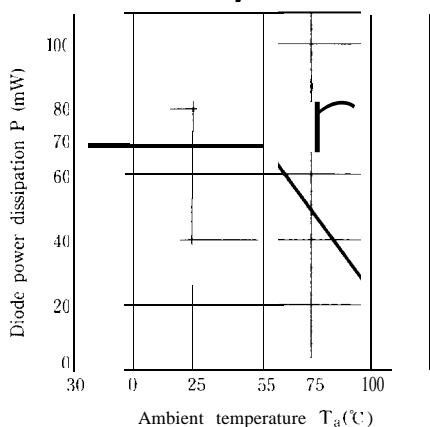


Fig. 3 Collector Power Dissipation vs. Ambient Temperature

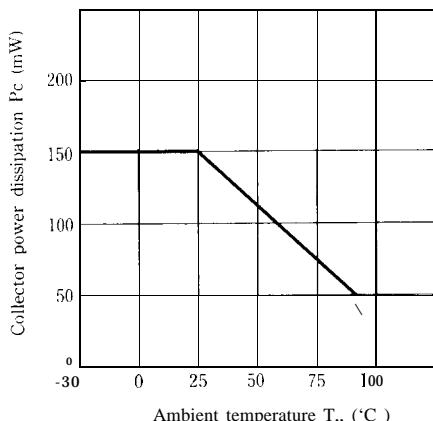


Fig. 5 Peak Forward Current vs. Duty Ratio

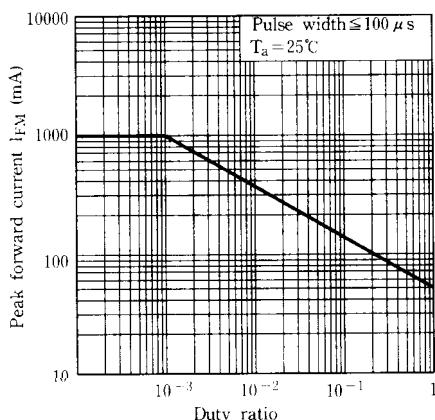


Fig. 7 Current Transfer Ratio vs. Forward Current

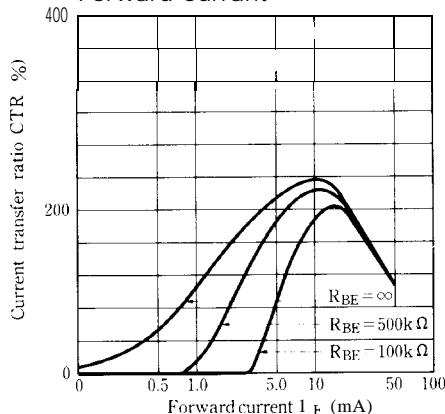


Fig. 4 Total Power Dissipation vs. Ambient Temperature

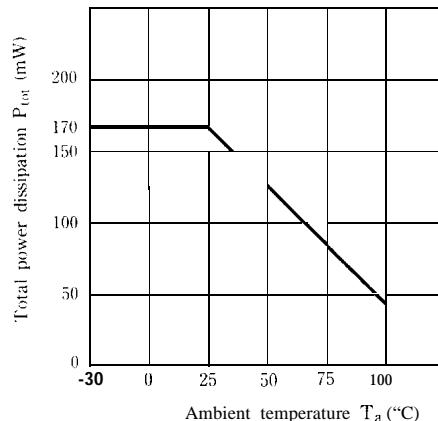


Fig. 6 Forward Current vs. Forward Voltage

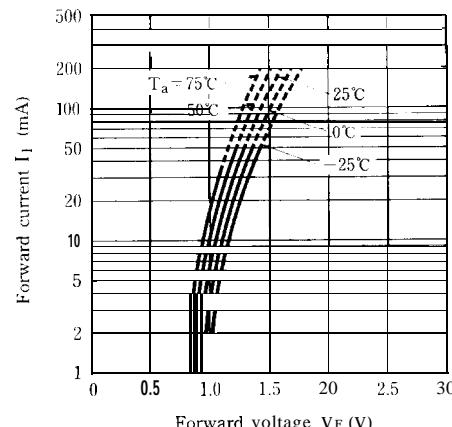


Fig. 8 Collector Current vs. Collector-emitter Voltage

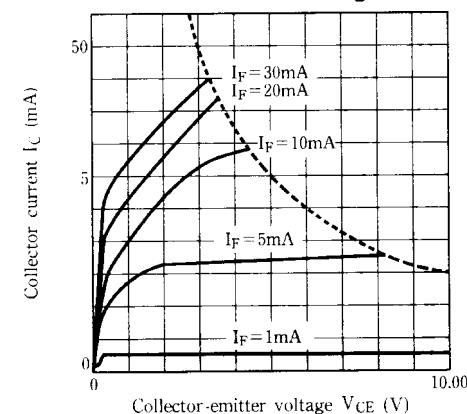


Fig. 9 Relative Current Transfer Ratio vs. Ambient Temperature

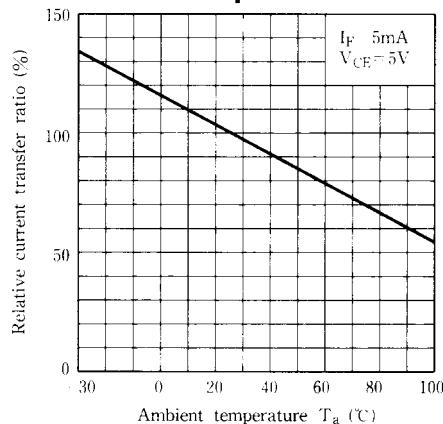


Fig.10 Collector-emitter Saturation Voltage vs. Ambient Temperature

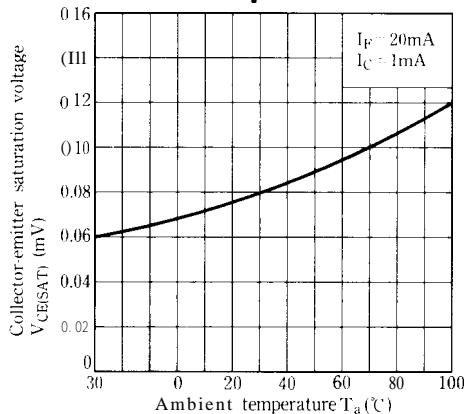


Fig.11 Collector Dark Current vs. Ambient Temperature

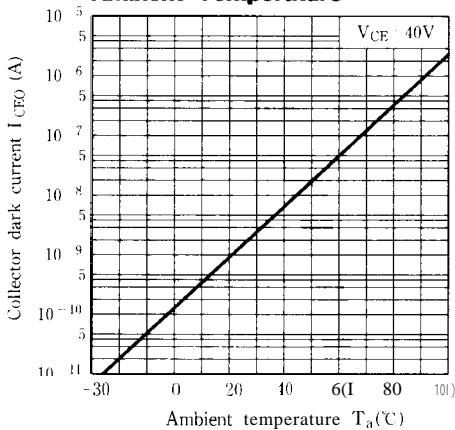


Fig.12 Response Time vs. Load Resistance

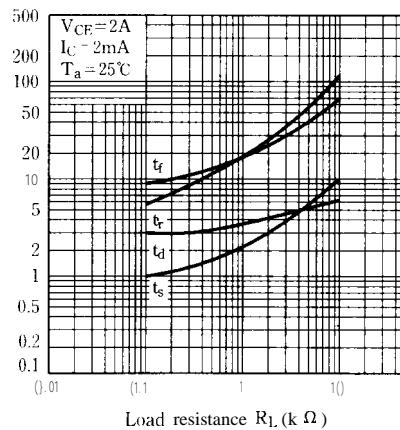
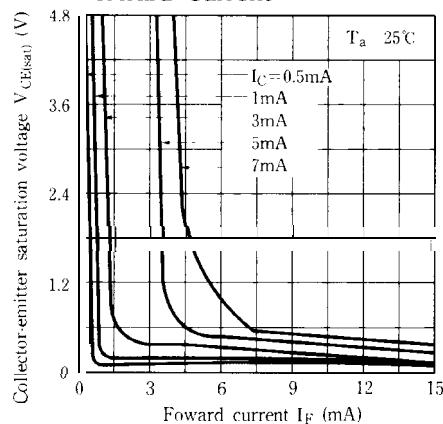


Fig.13 Collector-emitter Saturation Voltage vs. Forward Current



- Please refer to the chapter "Precautions for Use." (Page 78 to 93),